imall

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PNA4601M

Photodiode with Photodetection Function

For infrared remote control systems

Features

- Extension distance: 8 m or more
- External parts not required
- Adoption of visible light cutoff resin

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Operating supply voltage	V _{CC}	-0.5 to +7	V
Power dissipation	P _D	200	mW
Operating ambient temperature	T _{opr}	-20 to +75	°C
Storage temperature	T _{stg}	-40 to +100	°C
Soldering temperature *	T _{sol}	260	°C
Note) *: Less than 5 s			

Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating supply voltage	V _{CC}		4.7	5.0	5.3	V
Supply current	I _{CC}	No signal condition	1.8	2.4	3.0	mA
Maximum reception distance *1	L _{max}	all all all we we	8.0	10.0	5,	m
Low level output voltage *2	V _{OL}	$L \le 8.0 \text{ m}, I_{OL} = 400 \ \mu \text{A}$	N. Co	0.35	0.5	V
High level output voltage	V _{OH}	No signal condition, $I_{OH} = -10 \mu A$	4.75	4.80		V
Low level pulse width *1	T _{WL1}	L = 8.0 m, 16 pulse	200	400	600	μs
	T _{WL2}	L = 0.2 m, 16 pulse, $T_a = 65^{\circ}C \pm 3^{\circ}C$	100		700	μs
High level pulse width *1	T _{WH}	L = 8.0 m, 16 pulse	200	400	600	μs
Center frequency	f _O			36.7		kHz
Load resistance	R _L	ist and	15	20	25	kΩ

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1:Burst wave form figure 1.

*2:Constant wave form Figure 2. Carrier frequency: ${\rm f}_{\rm O}$

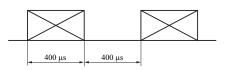


Figure 1

Carrier frequency: fo

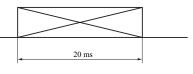
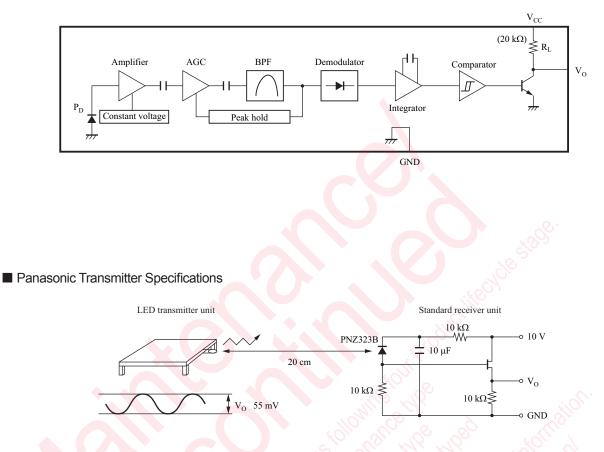


Figure 2

PNA4601M

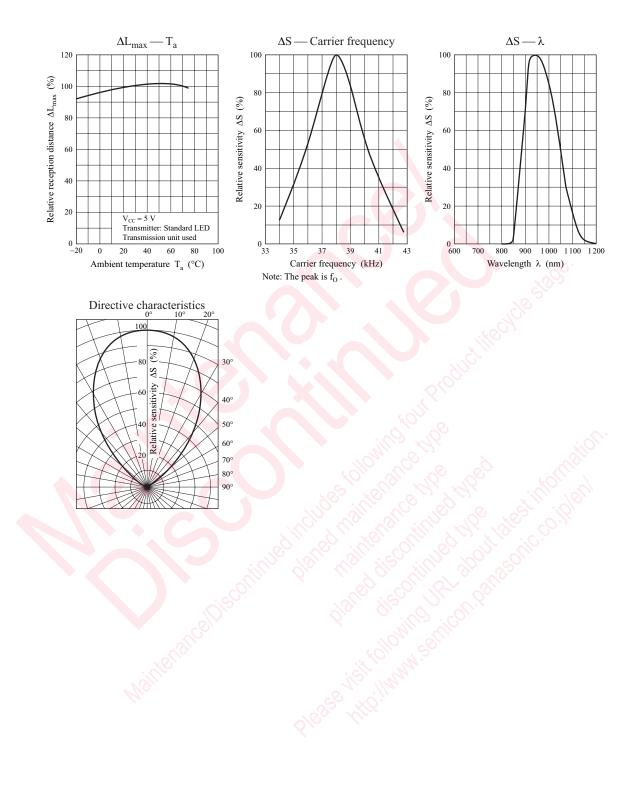
Panasonic

Block Diagram



- 1. The output of the LED transmitter unit is adjusted so that the output standard receiver unit, V_0 may be 55 mV when transmitting waves (duty = 50%) are output from the transmitter unit, where the sensitivity to infrared emitters (SIR) of PNZ323B is 0.53 μ A when the irradiance H is 12.45 μ W/cm².
- 2. The maximum detection distance of this specification is guaranteed by T_{WH} and T_{WL} being within the limits when constant 16 pulses are transmitted with the output of the transmitter unit corresponded to the maximum detection distance in the system above. (The maximum detection distance is measured in the darkness without disturbing noises.)

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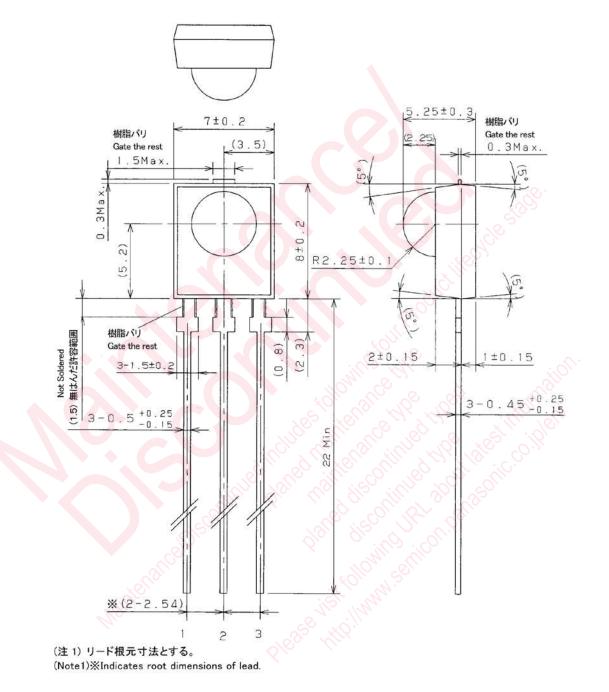


PNA4601M

Panasonic

Package (Unit: mm)





• Pin name

 $1: V_O$

2: GND

3: V_{CC}

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